DOCUMENT CHANGE REQUEST

DCR number 286	Changes required for: General	Originator: Steve Thacker
Date: 2006/10/11	Date sent: 2006/10/11	Organisation: ESA/ESTEC
Status: IMPLEMENTED		

Title:	Generic Specification for Discrete Semiconductor Components		
Number:	5000	Issue:	3

Other documents affected:

Page:

Page 17 Para 8.8.1 Seal, Fine Leak

Paragraph:

Page 17 Para 8.8.1 Seal, Fine Leak

Original wording:

Proposed wording:

Para 8.8.1 to be replaced in total with the following:

....

8.8.1 Seal, Fine Leak
MIL-STD-750, Test Method 1071, Condition H1 or H2.
This test is not applicable to double plug diodes.

....

Justification:

This change would return the fine leak seal test conditions back to the conditions previously specified in ESCC 5000 issue 1 (ESA/SCC 5000 issue 9A).
The current conditions in ESCC 5000 issue 3 are not harmonised with MIL-STD-750 and the leak rate limit is not specified for package volumes less than or equal to 0.05ccm.

Note - this change reflects the proposal instigated by the PSWG.

Attachments:
N/A
Modifications:
N/A
Approval signature:
Date signed:
2006-10-11